ASSOCIATION CONNECTINI ELECTRONICS INDUSTRIES	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					erials and N	als and Mfg Information				
upplier Inform	ation														
Company name*			Company unique ID			ī	Unique ID Authority				Respon	Response Date*			
onsemi											2025-0	2025-05-10			
Contact Name		Т	Title - Contact			]	Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewa	ards	P	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
uthorized Represe	ntative*	Т	Title - Representative			1	Phone - Representative*				Email	Email - Representative*			
Product-Env-Stewa	ırds	P	Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Requeste	Requester Item Number Mfr Ite		em Number Mfr Item Name				Effective Date	e Versi	ion	Manufacturing Site		Weight*	UOM	Unit Type	
		NRVTS126	VTS1260EMFST3 60V Low Leakage		e Trench Recti	ifier	2025-05-10		MY1			113.069	mg	Each	
Ianufacturing	Proccess Information	n													
Terminal Plating / Grid Array Material Term			erminal Base Alloy J-STD-020 MSI		SL Rating	Peak Pro	Peak Process Body Temperature Max Time at Pea		ak Tempera	nture Numb	er of Reflow Cyc	cles			
Matte Tin (Sn) - annealed		CU	CU Alloy 1		[		260		С	30	seco	nds 3			
omments															
vel 1 - maximum ti	ime at peak temperature o	during solde	ering is 10-3	0 seconds											
or more informatio	on regarding material con	nposition ple	ease refer to	page 3					· · · · · · · · · · · · · · · · · · ·						

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier neutrino a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	4.8	mg	Supplier	Zinc (Zn)	7440-66-6		0.0058	mg
			Supplier	Iron (Fe)	7439-89-6		0.1128	mg
			Supplier	Copper (Cu)	7440-50-8		4.68	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0014	mg
Die	0.713	mg	Supplier	Silicon (Si)	7440-21-3		0.713	mg
Die Attach Solder	11.9	mg	Supplier	Silver (Ag)	7440-22-4		0.2975	mg
			A	Lead (Pb)	7439-92-1	7a	11.0075	mg
			Supplier	Tin (Sn)	7440-31-5		0.595	mg
Lead Frame	47.44	mg	Supplier	Iron (Fe)	7439-89-6		0.0474	mg
			Supplier	Copper (Cu)	7440-50-8		47.3783	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0142	mg
Lead Frame plating	0.13	mg	Supplier	Silver (Ag)	7440-22-4		0.13	mg
Mold Compound-Black	47.136	mg		Epoxy resin	proprietary data		3.5352	mg
			Supplier	Phenolic Resin	Proprietary Data		1.1784	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		3.5352	mg
			Supplier	Carbon Black (C)	1333-86-4		0.2357	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		38.6515	mg
Plating	0.95	mg	Supplier	Tin (Sn)	7440-31-5		0.95	mg